BGA Heat Sink - High Performance maxiFLOW/superGRIP





ATS Part#: ATS-X50300G-C1-R0

Description: 30.00 x 30.00 x 12.50 mm BGA Heat Sink - High

Performance maxiFLOW/superGRIP

Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 30 x 30 mm components
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

Thermal Performance

| AIR VELOCITY | | @200 LFM 1.0 M/S | @300 LFM 1.5 M/S | @400 LFM 2.0 M/S | @500 LFM 2.5 M/S | @600 LFM 3.0 M/S | @700 LFM 3.5 M/S | @800 LFM 4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 4.4 °C/W | 3.6 °C/W | 3.1 °C/W | 2.8 °C/W | 2.5 °C/W | 2.4 °C/W | 2.2 °C/W |
| | Ducted Flow | 3.6 | N/A | N/A | N/A | N/A | N/A | N/A |

Product Detail





